

In the Claims

Please cancel claims 1-52 and 58-62, and amend claim 53 as follows.

53. (Amended) A semiconductor wafer fabrication system comprising:
- a sealed chamber for processing said semiconductor wafer; and a head assembly comprising:
    - a modulated light source exposing at least a portion of said semiconductor wafer to light having a wavelength and modulated at a frequency; and
    - a surface photovoltage sensor detecting a surface photovoltage induced at the surface of said semiconductor wafer in response to said light without contacting said wafer, wherein said photovoltage is used to calculate an electrical property of said semiconductor wafer.
  - said surface voltage sensor of said head assembly located within said sealed chamber.

Remarks

Applicants have amended the specification to describe the relationship between the present application and its prior related applications. Applicants have also amended all references to "a sensor probe assembly" in the specification to "a sensor head assembly" to obviate an objection to drawings in prior application 08/853,171 based on reference character "14" used to designate both a "sensor probe assembly" and a "sensor head assembly."

Applicants have canceled claims 1-52 and 58-62. Claim 53 has been amended.

No new matter has been added.